

VOLTERA ONE SYSTEM SPECIFICATIONS



Printing Specifications

Minimum trace width	0.2 mm
Minimum passive size	1005
Minimum pin-to-pin pitch (conductive ink)	0.8 mm
Minimum pin-to-pin pitch (solder paste)	0.5 mm
Resistivity	12 mΩ/sq @ 70 um height
Substrate material	FR4
Maximum board thickness	3 mm
Drilling Specifications	Max bit dia. – 2mm
	Min bit length – 38.1 mm

Soldering Specifications

Solder paste alloy	various
No Clean solder paste recommended	
MAX reflow bed temp	240°C

Print Bed

Print area	135 x 113.5 mm
Heated bed ramp rate ~2°C/s	